DSA2311

Crystal-less™ Configurable Two-Output Clock Generator for Automotive

Features

- Automotive AEC-Q100 Qualified
- Two Simultaneous CMOS Outputs
  - Output 1 Range: 2.3 MHz to 170 MHz
  - Output 2 Range: 2.3 MHz to 170 MHz
- Low RMS Phase Jitter: <1 ps (typ.)
- High Stability: ±20 ppm, ±25 ppm, ±50 ppm
- Wide Temperature Range:
  - Automotive Grade 1: –40°C to +125°C
  - Automotive Grade 2: –40°C to +105°C
  - Automotive Grade 3: –40°C to +85°C
- High Supply Noise Rejection: –50 dBc
- High Shock and Vibration Immunity
  - Qualified to MIL-STD-883
- High Reliability
  - 20x higher MTBF than crystal-based clock generator designs
- Supply Range of 2.25 to 3.63V
- Lead-Free and RoHS Compliant

Applications

- Automotive Infotainment
- Automotive ADAS
- Automotive Camera Module
- Automotive LIDAR and RADAR

Benefits

- Replace High Temperature Crystals and Quartz Oscillators

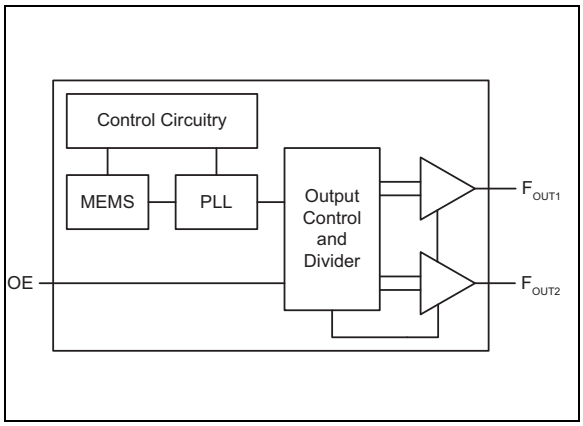
General Description

The DSA2311 is a crystal-less™ clock generator that is factory-configurable to simultaneously output two separate frequencies from 2.3 MHz to 170 MHz. The clock generator uses proven silicon MEMS technology to provide low jitter and high frequency stability across a wide range of supply voltages and temperatures. By eliminating the external quartz crystal, crystal-less clock generators significantly enhance reliability and accelerate product development, while meeting stringent clock performance criteria for a variety of consumer electronics, communications, and storage applications.

DSA2311 has an Output Enable/Disable feature that allows it to disable the outputs when OE is low. The device is available in a space-saving 6-pin 2.5 mm x 2.0 mm crystal-less VDFN package that uses only a single external bypass capacitor.

The two output frequencies can be customized by using Clockworks:
http://clockworks.microchip.com/timing

Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Input Voltage, V_{IN} .....–0.3V to V_{DD} +0.3V
Supply Voltage .....–0.3V to + 4.0V
ESD Protection (HBM) .....4 kV
ESD Protection (CDM) .....1.5 kV

† Notice: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: ELECTRICAL CHARACTERISTICS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Supply Voltage (Note 1)	V_{DD}	2.25	—	3.6	V	—
Supply Current (Note 2)	I_{DD}	—	21	23	mA	EN pin low. All outputs disabled.
Frequency Stability (Note 3)	Δf	—	—	±20	ppm	Includes frequency variations due to initial tolerance, temperature, and power supply voltage.
		—	—	±50		
Aging	Δf	—	—	±5	ppm	One year at +25°C
Start-up Time (Note 4)	t_{SU}	—	—	5	ms	T = +25°C
Input Logic Levels	V_{IH}	0.75 x V_{DD}	—	—	V	Input logic high
	V_{IL}	—	—	0.25 x V_{DD}		Input logic low
Output Disable Time	t_{DA}	—	—	5	ns	—
Output Enable Time	t_{EN}	—	—	20	ns	—
Pull-Up Resistor (Note 2)	—	—	40	—	kΩ	Pull-up exists on all digital IO
Output Logic Levels	V_{OH}	0.9 x V_{DD}	—	—	V	Output logic high, I = ±6 mA
	V_{OL}	—	—	0.1 x V_{DD}		Output logic low, I = ±6 mA
Output Transition Rise Time	t_R	—	1.1	2.0	ns	20% to 80%; C_L = 15 pF
Output Transition Rise Time	t_F	—	1.4	2.0		20% to 80%; C_L = 15 pF
Frequency	f_0	2.3	—	170	MHz	Grade 3 temp. range
		3.3	—	100		Grade 1 temp. range
		3.3	—	170		Grade 2 temp. range
Output Duty Cycle	SYM	45	—	55	%	—
Period Jitter (Note 5)	J_{PER}	—	3	—	ps_{RMS}	F_{O1} = F_{O2} = 25 MHz
Integrated Phase Noise	J_{CC}	—	0.3	—	ps_{RMS}	200 kHz to 20 MHz @ 25 MHz
		—	0.38	—		100 kHz to 20 MHz @ 25 MHz
		—	1.7	2		12 kHz to 20 MHz @ 25 MHz

Note 1: Pin 4 V_{DD} should be filtered with a 0.01 µF capacitor.

2: Output is enabled if Enable pad is floated or not connected. Operating current = disabled current + ΔI_{DD} from F_{OUT1} + ΔI_{DD} from F_{OUT2}. See graph for more information.

3: For other ppm stabilities, please contact the factory.

4: t_{SU} is time to 100 ppm stable output frequency after V_{DD} is applied and outputs are enabled.

5: Period jitter includes crosstalk from adjacent output.

TEMPERATURE SPECIFICATIONS (Note 1)

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Operating Temperature Range (T)	T_A	–40	—	+85	°C	Ordering Option I
	T_A	–40	—	+105	°C	Ordering Option L
	T_A	–40	—	+125	°C	Ordering Option A
Junction Operating Temperature	T_J	—	—	+150	°C	—
Storage Temperature Range	T_A	–40	—	+150	°C	—
Soldering Temperature Range	T_S	—	—	+260	°C	40 sec. max.

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above +150°C can impact the device reliability.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	ENABLE	Output Enable for both CLK0 and CLK1.
2	N/C	Do not connect.
3	GROUND	Ground.
4	CLK0	Clock Output 0 (CMOS).
5	CLK1	Clock Output 1 (CMOS).
6	VDD	Supply Voltage.

3.0 OUTPUT WAVEFORM

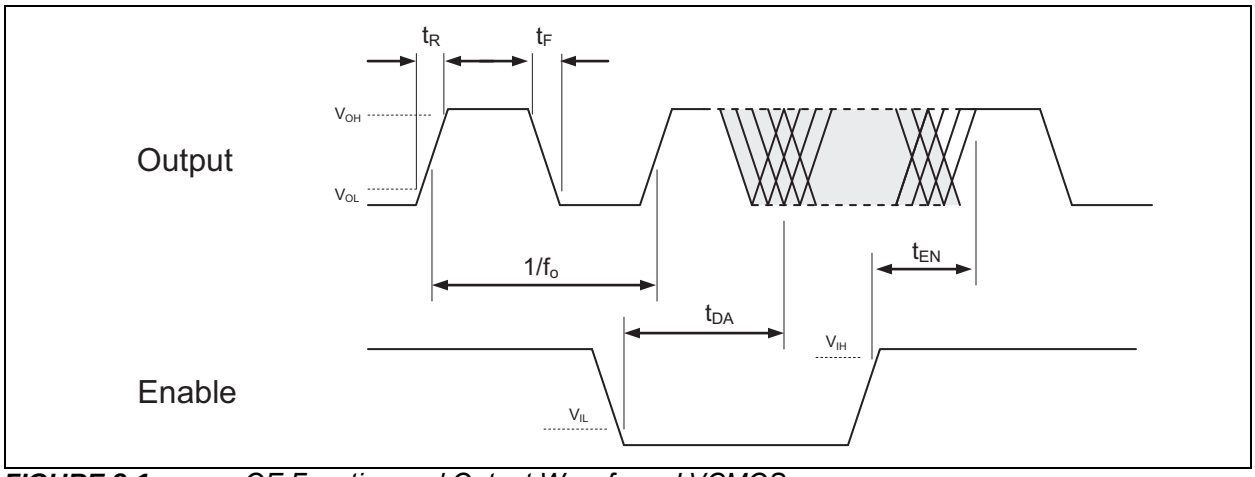


FIGURE 3-1: *OE Function and Output Waveform: LVCMOS.*

4.0 CURRENT CONSUMPTION

Total Current = Disabled Current + ΔI_{DD} F_{OUT1} + ΔI_{DD} F_{OUT2}

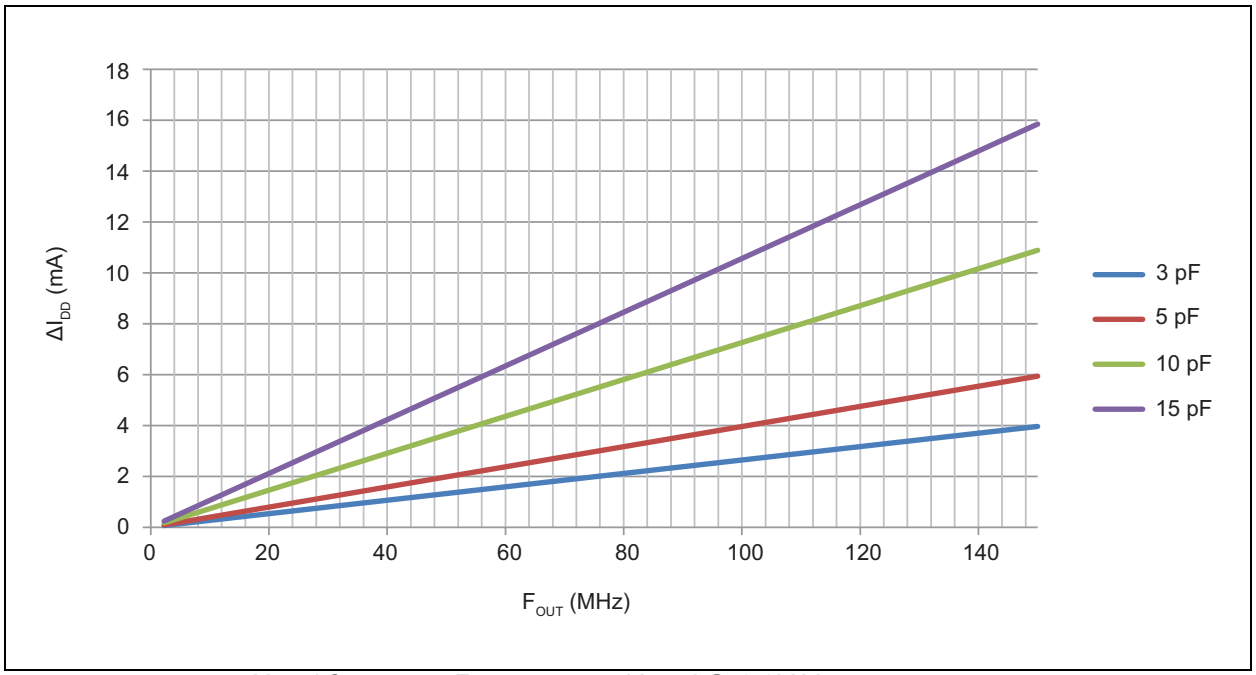


FIGURE 4-1: *ΔI_{DD} / Output vs. Frequency and Load @ 3.3V V_{DD}.*

5.0 SOLDER REFLOW PROFILE

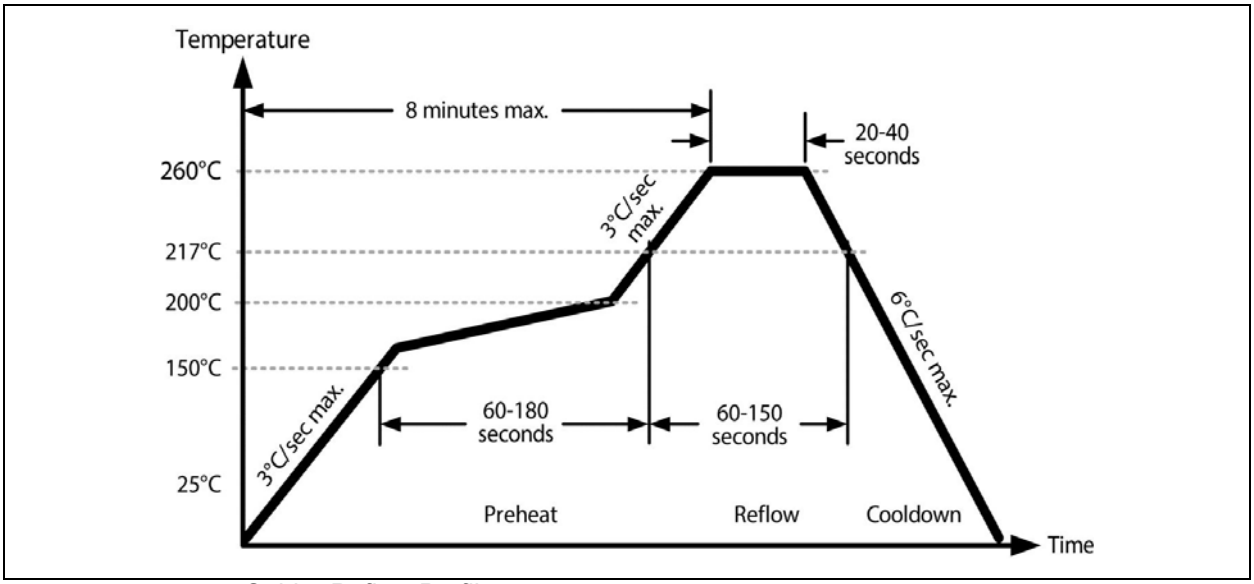


FIGURE 5-1: *Solder Reflow Profile.*

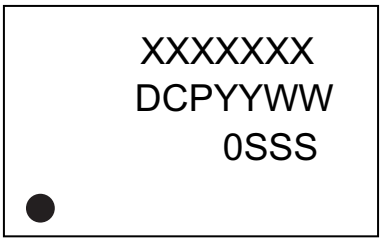
TABLE 5-1: SOLDER REFLOW

MSL 1 @ 260°C Refer to JSTD-020C	
Ramp-Up Rate (200°C to Peak Temp.)	3°C/sec. max.
Preheat Time 150°C to 200°C	60 to 180 sec.
Time Maintained above 217°C	60 to 150 sec.
Peak Temperature	255°C to 260°C
Time within 5°C of Actual Peak	20 to 40 sec.
Ramp-Down Rate	6°C/sec. max.
Time 25°C to Peak Temperature	8 minutes max.

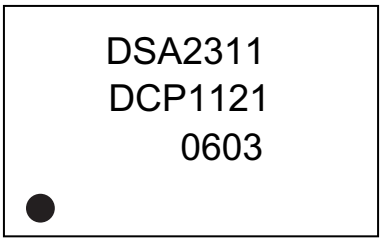
6.0 PACKAGING INFORMATION

6.1 Package Marking Information

6-Lead VDFN*



Example

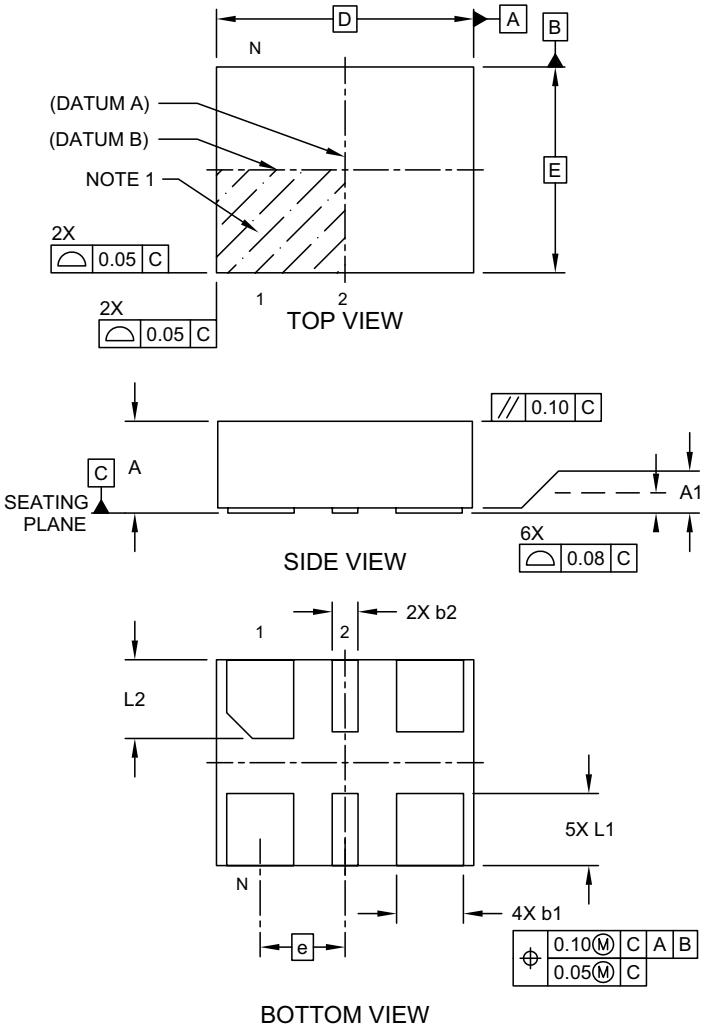


Legend:	XX...X	Product code, customer-specific information, or frequency in MHz without printed decimal point
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
	●, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.	
	Underbar (_) and/or Overbar (¯) symbol may not be to scale.	

6-Lead VDFN 2.5 mm x 2.0 mm Package Outline and Recommended Land Pattern

6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

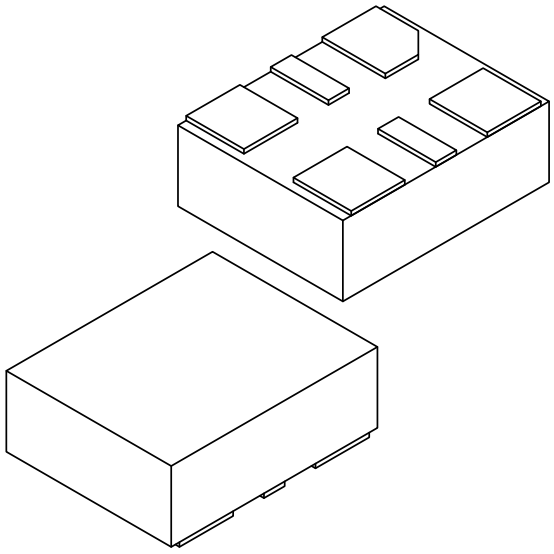
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1005A Sheet 1 of 2

6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		6	
Pitch	e		0.825 BSC	
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.02	0.05
Overall Length	D		2.50 BSC	
Overall Width	E		2.00 BSC	
Terminal Width	b1	0.60	0.65	0.70
Terminal Width	b2	0.20	0.25	0.30
Terminal Length	L1	0.60	0.70	0.80
Terminal Length	L2	0.665	0.765	0.865

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

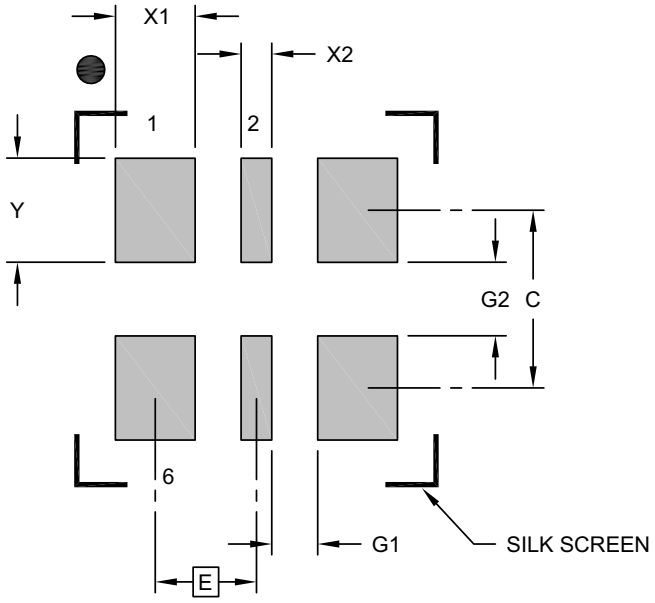
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1005A Sheet 2 of 2

6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.825 BSC		
Contact Pad Width (X4)	X1			0.65
Contact Pad Width (X2)	X2			0.25
Contact Pad Length (X6)	Y			0.85
Contact Pad Spacing	C		1.45	
Space Between Contacts (X4)	G1	0.38		
Space Between Contacts (X3)	G2	0.60		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3005A

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (March 2018)

- Initial release of DSA2311 as Microchip data sheet DS20005893A.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

PART NO.	X	X	X	RXXXX	X
Device	Package	Temperature Range	Stability	Frequency	Packing Option

Device:	DSA2311:	Crystal-less Configurable Two-Output Clock Generator for Automotive	
Package:	K	=	6-LEAD 2.5 mm x 2.0 mm VDFN
Temperature Range:	A	=	–40°C to +125°C (Grade 1)
	L	=	–40°C to +105°C (Grade 2)
	I	=	–40°C to +85°C (Grade 3)
Stability:	1	=	±50 ppm
	2	=	±25 ppm
	3	=	±20 ppm
Frequency:	Rxxxx	=	Custom Frequency Code
Packing Option:	<blank>	=	Tube
	T	=	Tape & Reel

Output Clock Frequencies

Output frequencies are factory-configured to individual customer and product requirements, subject to output control and divider limitations. Contact sales with your custom frequency needs.

http://clockworks.microchip.com/timing/

Frequency Code	F_{OUT1} (MHz)	F_{OUT2} (MHz)
R0001	127	127
R0002	25	125

Examples:

a) DSA2311KL1-Rxxxx — Crystal-less Configurable Two-Output Clock Generator, 6-LD VDFN, Grade 2 Temp. Range, ±50 ppm Stability, Custom Frequency (F_{OUT1} and F_{OUT2}), Tube

b) DSA2311KI3-Rxxxx — Crystal-less Configurable Two-Output Clock Generator, 6-LD VDFN, Grade 3 Temp. Range, ±20 ppm Stability, Custom Frequency (F_{OUT1} and F_{OUT2}), Tube

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

NOTES:

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